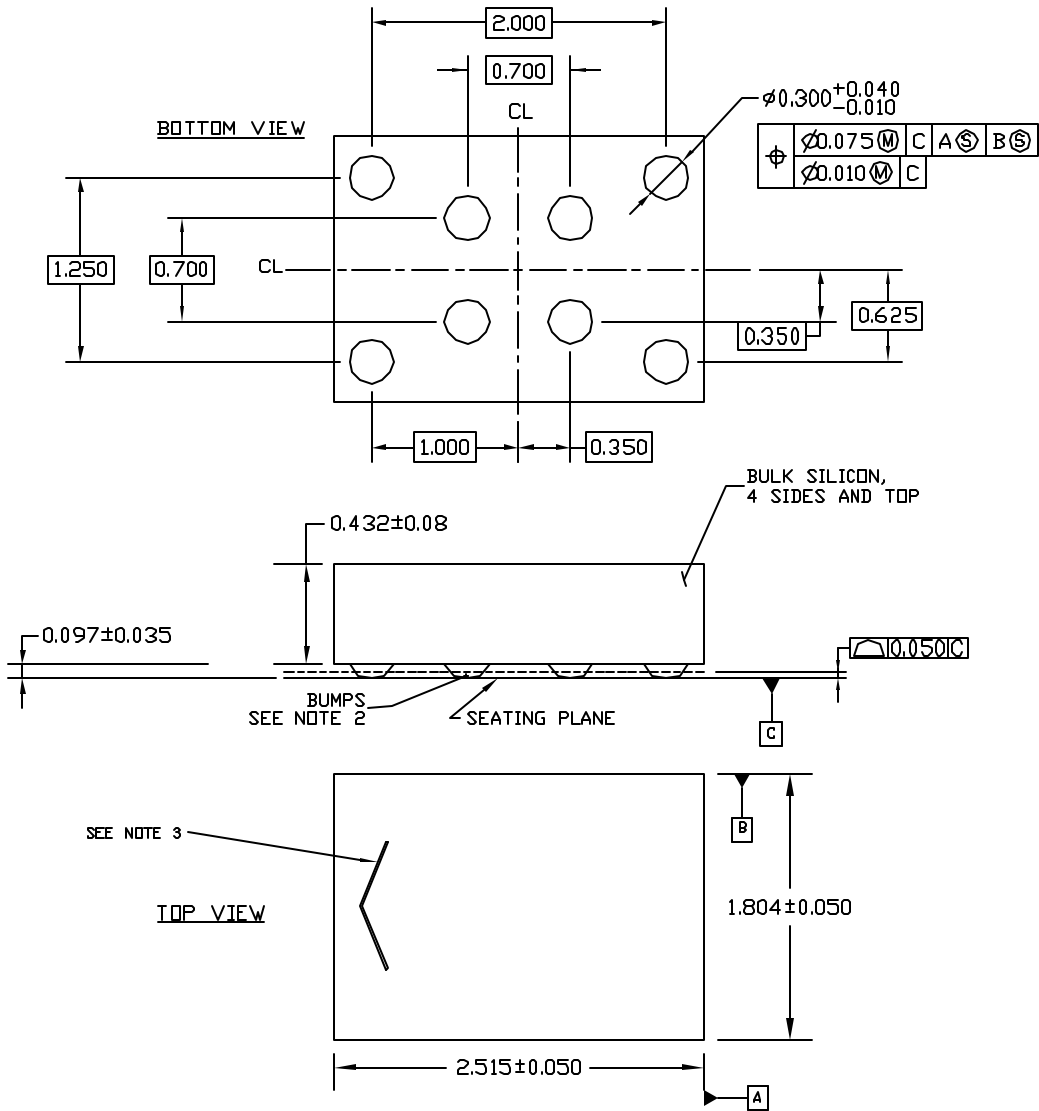


REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE		



SIGNATURE		DATE			
QA APVD:					
ENGR MGR:				DS2432X FLIP CHIP PACKAGE, 8-BUMP, 0,70 MM PITCH, PKG CODE - BF823-1	
ENGR BY:					
B. MCCARTY 9/11/00					
CHECK BY:		SIZE	FSCM NO.	DWG NO.	REV
S CHINNUSAMY 10/06		A		56-G7011-001	A
DRAWN BY:		SCALE		SHEET	
B. MCCARTY 9/8/00		NONE		1 / 2	

NOTES:

1. DIMENSIONS: MM [INCH]
2. BUMP MATERIAL: 5 Sn / 95 Pb
3. LASER MARK
4. LANDING PAD DIAMETER NOT DEFINED BY SOLDER RESIST; FOR PAD CENTER COORDINATES AND CONNECTIONS, SEE TABLE 1
5. UNDERFILL RECOMMENDED FOR RELIABILITY ON FR4 SUBSTRATE

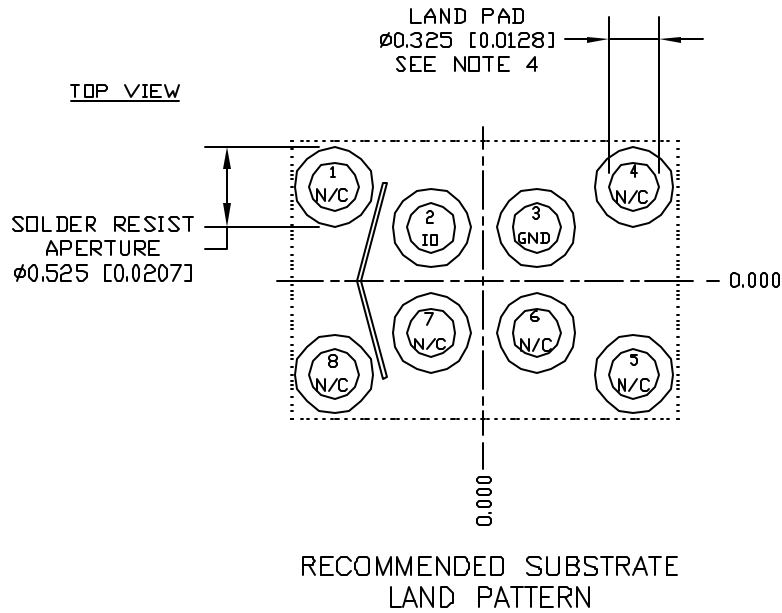


TABLE 1. LAND PAD CONNECTIONS AND CENTER COORDINATES

NUMBER	NAME	MM		INCH	
		X	Y	X	Y
1	N/C	-1	0.625	-0.0394	0.0246
2	I/O	-0.35	0.35	-0.0138	0.0138
3	GND	0.35	0.35	0.0138	0.0138
4	N/C	1	0.625	0.0394	0.0246
5	N/C	1	-0.625	0.0394	-0.0246
6	N/C	0.35	-0.35	0.0138	-0.0138
7	N/C	-0.35	-0.35	-0.0138	-0.0138
8	N/C	-1	-0.625	-0.0394	-0.0246

SIZE	FSCM NO.	DWG NO.	REV
		56-G7011-001	A
SCALE	SHEET		2 / 2